SECTION II—CLAIMS

1.-28. (Canceled)

29. (Previously Presented) A process of tuning an oscillator, the process comprising:

providing an oscillator including

at least one pedestal formed on a substrate,

a vibrating portion of the oscillator supported by the at least one pedestal such that the vibrating portion is not in contact with the substrate, and

a plurality of spaced-apart stacks on one side of the vibrating portion;

determining a first resonant frequency of the oscillator member; and

adjusting the resonant frequency of the oscillator by removing at least one of the plurality of spaced-apart stacks on the vibrating portion.

30. (Previously Presented) The process of claim 29 wherein removing at least one of the plurality of spaced-apart stacks comprises directing radiant energy at the at least one spaced-apart stack to be removed.

31. (Previously Presented) The process of claim 30 wherein the radiant energy source is a focused ion beam or a laser.

32. (Previously Presented) The process of claim 29 wherein the vibrating portion is a cantilever beam, a bridge beam, or a membrane.

33. (Previously Presented) The process of claim 29 wherein the oscillator further comprises a drive electrode positioned between the vibrating portion and the substrate.

34. (Previously Presented) A process of tuning an oscillator, the process comprising:

providing an oscillator, the oscillator including

at least one pedestal formed on a substrate, and

a vibrating portion of the oscillator supported by the at least one pedestal such that the vibrating portion is not in contact with the substrate;

determining a first resonant frequency of the oscillator; and

adjusting the resonant frequency of the oscillator by forming one or more structures on one side of the vibrating portion.

35. (Previously Presented) The process of claim 34 wherein forming at least one structure on the vibrating portion comprises precipitating a vapor on the vibrating portion.

36. (Previously Presented) The process of claim 35 wherein precipitating a vapor on the vibrating portion comprises directing radiant energy at the vibrating portion in the presence of a deposition vapor.

37. (Previously Presented) The process of claim 36 wherein the radiant energy source is a focused ion beam or a laser.

38. (Previously Presented) The process of claim 34 wherein the vibrating portion is a cantilever beam, a bridge beam, or a membrane.

39. (Previously Presented) The process of claim 34 wherein the oscillator further comprises a drive electrode positioned between the vibrating portion and the substrate.

40. (New) A process of tuning an oscillator, the process comprising:

providing an oscillator including

at least one pedestal formed on a substrate,

a vibrating portion of the oscillator supported by the at least one pedestal such that the vibrating portion is not in contact with the substrate, and

one or more structures on one side of the vibrating portion;

determining a first resonant frequency of the oscillator member; and

adjusting the resonant frequency of the oscillator by altering the structures on the vibrating portion.

41. (New) The process of claim 40 wherein altering the structures on the vibrating portion comprises removing at least one of the structures.

42. (New) The process of claim 41 wherein removing at least one of the structures comprises directing radiant energy at the at least one structure to be removed.

43. (New) The process of claim 40 wherein altering the structures on the vibrating portion comprises forming at least one structure on the vibrating portion.

44. (New) The process of claim 43 wherein forming at least one structure on the vibrating portion comprises precipitating a vapor on the vibrating portion.

45. (New) The process of claim 44 wherein precipitating a vapor on the vibrating portion comprises directing radiant energy at the vibrating portion in the presence of a deposition vapor.